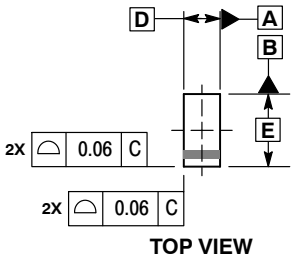
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

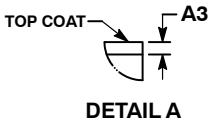
DSN2, 0.6x0.3, 0.4P, (0201)
CASE 152AS
ISSUE A

SCALE 8:1

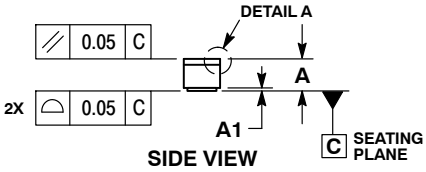
DATE 23 JAN 2014



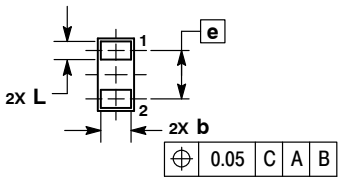
TOP VIEW



DETAIL A



SIDE VIEW

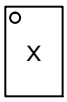


BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.24	0.30
A1	0.00	0.01
A3	0.04 REF	
b	0.20	0.25
D	0.30 BSC	
E	0.60 BSC	
e	0.40 BSC	
L	0.10	0.18

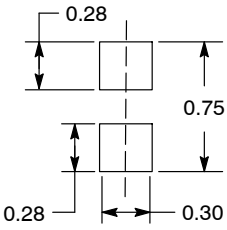
GENERIC MARKING DIAGRAM*



X = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G”, may or not be present.

MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

See Application Note AND8398/D for more mounting details

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	**DSN2, 0.6X0.3, 0.4P, (0201)**		**PAGE 1 OF 1**